	1	2	3	4	5	6	
А							A
			CI2	D5 DFLS1200-7 0.85V DNP 2 DNP 2 DNP D4 3 PMEG6010CEH,115 0.57V 2.2µF 1.00k	15VP +15V, 50mA 2.2μF ≥2.00k 5VP +5V, 100mA		
В		-		7 C10 C10 2.2µF ₹1.00k	C9 2.2µF 2.2µF 2.00k C9 2.2µF C9 2.00k C9 2.2µF C9 2.00k C9 2.2µF C9 2.2µF C9 2.2µF C9 C9 C9 C9 C9 C9 C9 C9 C9 C9 C9 C9 C9		В
		VIN 17V-32V Vin Fsw= R5 10V 1210 0.1µF 0.1µF 100V 0805	2 2 2 2 2 2 2 2 2 2 2 2 2 2		i		
С			GND FB	R2 20.0k			с
D			ors do not warrant the accuracy or completeness of this specification or an e specifications, will be suitable for your application or fit for any particular sign is production worthy. You should completely validate and test your de	ny information contained therein. Texas Instruments and/or its licensors do not purpose, or will operate in an implementation. Texas Instruments and/or its esign implementation to confirm the system functionality for your application.	Designed for: Pub   Project Title: Char   Number: XX#### Rev: E1 Sheet Title:   SVN Rev: Not in version control Assembly Variant   Drawn By: File: Flybuck Que File: Flybuck Que   Engineer: Enter name of project lead Contact: http://www.sec.	lic Release Mod. Date: 8/19/2013 nge in menu Project Project Options Parameter i quad Sheet: 1 of 1 id Dual rev2.SchDoc Size: B http w.ti.com/support © Texar	D TEXAS INSTRUMENTS p://www.ti.com is Instruments 2012
	1	2	3	4	5	6	

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